
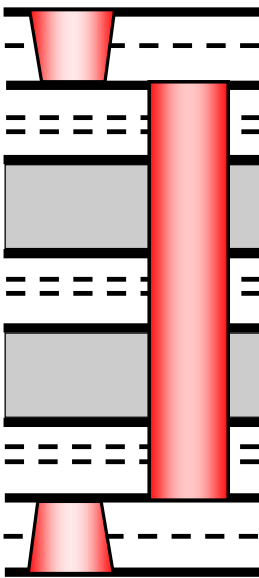


Build Up HDI (Standard)											
HDI08_1+6b+1_1,45_35_engl		8 - Layers Core: 0,36 mm Cu 35/35 µm									
WE-Articel No.:		1 + 6B + 1									
Customer:											
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements		
Customer	WE							[µm]	[µm]		
	TOP/VS						Foil	12 µm	1) ¹⁾	12	
									1 x 1080	60	
	2						Foil	9 µm		30	
									2 x 1080	133	
	3							35 µm		33	
							0,360 mm			360	
	4							35 µm		33	
									2 x 1080	124	
	5							35 µm		33	
							0,360 mm			360	
	6							35 µm		33	
									2 x 1080	133	
	7						Foil	9 µm		30	
									1 x 1080	60	
	BOT/RS			Foil	12 µm	1) ¹⁾	12				
				1) copper thickness outer layers: appr. 55 µm							
total material thickness:							1446				
Note: Lamination thickness for Prepregs depending on layout characteristics.											
final lamination thickness:	1,45	+/-	0,12	mm			Date:	Engineer:			
thickness with electro plated Cu:	1,54	+/-	0,15	mm							
total thickness with soldermask	1,60	+/-	0,17	mm							
customer requirement		+/-		mm	point:						
prepared:		checked:		approved:		revision					
on	by	on	by	on	by			page: 14+			
25.04.2006	S. Keller	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00					